

perlMakeModelTables2.pl is being run

nmos	BSIM4.3.0 Model Selectors/Controllers											
	180nm	130nm	130nm	90nm	90nm	65nm	65nm	45nm	45nm	32nm	22nm	
LEVEL	49	54	49	54	49	54	54	54	54	54	54	SPICE3 model selector
VERSION	4	4	4	4	4	4	4	4	4	4	4	Model version
BINUNIT	2	1	2	1	2	1	1	1	1	1	1	Binning unit
PARAMCHK	1	1	1	1	1	1	1	1	1	1	1	Switch for parameter value check
MOBMOD	1	0	1	0	1	0	0	0	0	0	0	Mobility model
RDSMOD	0	0	0	0	0	0	0	0	0	0	0	Bias-dependent source/drain resistance model
IGCMOD	1	1	1	1	1	1	1	1	1	1	1	Gate-to-channel tunneling current model
IGBMOD	1	1	1	1	1	1	1	1	1	1	1	Gate-to-substrate tunneling current model
CAPMOD	2	2	2	2	2	2	2	2	2	2	2	Capacitance model
RGATEMOD	1	1	1	1	1	1	1	1	1	1	1	Gate resistance model
RBODYMOD	1	1	1	1	1	1	1	1	1	1	1	Substrate resistance network model
TRNQSMOD	0	0	0	0	0	0	0	0	0	0	0	Transient NQS model
ACNQSMOD	0	0	0	0	0	0	0	0	0	0	0	AC small-signal NQS model
FNQIMOD	1	1	1	1	1	1	1	1	1	1	1	Flicker noise model
TNOIMOD	0	0	0	0	0	0	0	0	0	0	0	Thermal noise model
DIOMOD	1	1	1	1	1	1	1	1	1	1	1	Source/drain junction diode IV
TEMPMOD	1	1	1	1	1	1	1	1	1	1	1	Temperature mode selector
PERMOD	1	1	1	1	1	1	1	1	1	1	1	Whether PS/PD includes the gate-edge perimeter
GEOMOD	1	1	1	1	1	1	1	1	1	1	1	Geometry-dependent parasitics
RGEOMOD	1	1	1	1	1	1	1	1	1	1	1	Source/drain diffusion resistance and contact model
=====												
Process Parameters												
EPSROX	3.9	3.9	3.9	3.9	3.9	3.9	3.9	3.9	3.9	3.9	3.9	Gate dielectric constant relative to vacuum 3.9 (SiO2)
TOXE	2.25e-09	2.05e-09	2.05e-09	1.85e-09	1.85e-09	1.75e-09	1.75e-09	1.4e-09	1.65e-09	1.2e-09	1.2e-09	Electrical gate equivalent oxide thickness
TOXP	1.4e-09	1.4e-09	1.4e-09	1.4e-09	1.4e-09	1.1e-09	1.1e-09	7e-10	1.1e-09	9e-10	9e-10	Physical gate equivalent oxide thickness
TOXM	2.25e-09	2.05e-09	2.05e-09	1.85e-09	1.75e-09	1.75e-09	1.4e-09	1.65e-09	1.2e-09	1.2e-09	1.2e-09	Tox at which parameters are extracted
DTOX	6.5e-10	6.5e-10	6.5e-10	6.5e-10	6.5e-10	6.5e-10	6.5e-10	6.5e-10	6.5e-10	3e-10	3e-10	Defined as (TOXE-TOXP)
XJ	6e-08	3.92e-08	4.5e-08	2.8e-08	4e-08	1.96e-08	2.5e-08	1.4e-08	2e-08	1e-08	7.2e-09	S/D junction depth
GAMMA1												(g1 in equation) Body-effect coefficient near the surface
GAMMA2												(g2 in equation) Body-effect coefficient in bulk
NDEP	1.54e+18	1.94e+18	1.94e+18	2.54e+18	2.6e+18	3.24e+18	2.8e+18	4.12e+18	1.2e+19	1.2e+19	1.2e+19	Channel doping concentration at depletion edge for zero body bias
NSUB												Substrate doping concentration
NGATE	5e+20	2e+20	5e+20	2e+20	5e+20	2e+20	5e+20	2e+20	5e+20	2e+20	2e+20	Poly Si gate doping concentration
NSD		2e+20	2e+20	2e+20	2e+20	2e+20	1e+20	2e+20	1e+20	2e+20	2e+20	Source/drain doping concentration
VBX												Vbs at which the depletion region width equals XT
XT												Doping depth 1.55e-7m Yes
RSH	5	5	5	5	5	5	5	3	5	5	5	Source/drain sheet resistance
RSHG	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	0.4	Gate electrode sheet resistance
=====												
Basic Model Parameters												
VTH0	0.3999	0.3782	0.332	0.397	0.2607	0.423	0.22	0.466	0.22	0.5088	0.5118	VTH0 Long-channel threshold voltage at Vbs=0 0.7V (NMOS) -0.7V (PMOS) Yes Note-4
VFB		-0.55		-0.55		-0.55	-0.55	-0.55	-0.55	-0.55	-1.058	Flat-band voltage -1.0V Yes Note-4
PHIN		0		0		0	0	0	0	0	0	Non-uniform vertical doping effect on surface potential 0.0V Yes -
K1	0.5613	0.4	0.3661	0.4	0.395	0.4	0.43	0.4	0.35	0.4	0.4	First-order body bias coefficient 0.5V1/2 Yes Note-5
K2	0.01	0.01	0	0.01	0.01	0.01	0.01	0	0.05	0	0	Second-order body bias coefficient 0.0 Yes Note-5
K3	0	0	0	0	0	0	0	0	0	0	0	Narrow width coefficient 80.0 Yes -
K3B	0	0	0	0	0	0	0	0	0	0	0	Body effect coefficient of K3 0.0 V-1 Yes -
W0	0	2.5e-06	0	2.5e-06	0	2.5e-06	2.5e-06	2.5e-06	2.5e-06	2.5e-06	2.5e-06	Narrow width parameter 2.5e-6m Yes -
LPE0	0	0	0	0	0	5.75e-08	0	5.75e-08	0	0	0	Lateral non-uniform doping parameter at Vbs=0 1.74e-7m Yes -
LPEB	0	0	0	0	0	2.3e-10	0	2.3e-10	0	0	0	Lateral non-uniform doping effect on K1 0.0m Yes -
VBM												Maximum applied body bias in VTH0 calculation -3.0V Yes -
DVT0	8	1	8.75	1	1	1	3.5	1	2.8	1	1	First coefficient of short-channel effect on Vth 2.2 Yes -
DVT1	0.75	2	0.7	2	0.4	2	0.52	2	0.52	2	2	Second coefficient of short-channel effect on Vth 0.53 Yes -
DVT2	0.008	-0.032	0.05	-0.032	0.15	-0.032	-0.032	0	-0.032	0	0	Body-bias coefficient of short-channel effect on Vth -0.032V-1 Yes -
DVT3		1.2e-09		1.2e-09		1e-09	1.2e-09	1e-10	1e-07	1e-11	1e-11	First coefficient of drain-induced Vth shift due to for long-channel pocket devices 0.0m Yes
DVTP1		0.1		0.1		0.1	0.1	0.1	0.05	0.1	0.1	First coefficient of drain-induced Vth shift due to for long-channel pocket devices 0.0V-1 Yes -
DVTW0	0	0	0	0	0	0	0	0	0	0	0	First coefficient of narrow width effect on Vth for small channel length 0.0 Yes -
DVTW1	0	0	0	0	0	0	0	0	0	0	0	Second coefficient of narrow width effect on Vth for small channel length 5.3e6m-1 Yes -
DVTW2	0	0	0	0	0	0	0	0	0	0	0	Body-bias coefficient of narrow width effect for small channel length -0.032V-1 Yes -
U0	0.035	0.05928	0.0134	0.0547	0.018	0.0491	0.06	0.04398	0.032	0.0389	0.0181	Low-field mobility 0.067 m2/(Vs) (NMOS); 0.025 m2/(Vs) PMOS Yes -
UA	-7e-10	6e-10	-1.8e-09	6e-10	-6e-10	6e-10	1e-10	6e-10	1.6e-10	6e-10	-5e-10	Coefficient of first-order mobility degradation due to vertical field 1.0e-9m/V for MOBMOD=0
UB	0.8	1.2e-18	0.52	1.2e-18	0.6	1.2e-18	1e-17	1.2e-18	1.1e-17	1.2e-18	1.7e-18	Coefficient of second-order mobility degradation due to vertical field 1.0e-19m2/V2 Yes -
UC	-5.25e-11	0	-3e-11	-3e-11	-3e-11	0	-3e-11	0	-3e-11	0	0	Coefficient of mobility degradation due to body-bias effect -0.0465V-1 for MOBMOD=1; -0.0465e-9
EU												Exponent for mobility degradation of MOBMOD=2 1.67 (NMOS); 1.0 (PMOS) -
VSAT	1.38e+05	1.004e+05	1.35e+05	1.138e+05	1.1e+05	1.243e+05	1.2e+05	1.474e+05	1.1e+05	1.785e+05	2e+05	Saturation velocity 8.0e4m/s Yes -
A0	30	30	30	30	30	30	30	30	30	30	30	Coefficient of channel-length dependence of bulk charge effect 1.0 Yes -
AGS	-0.01	1e-20	-0.1	1e-20	-0.01	1e-20	1e-20	0	1e-20	0	0	Coefficient of Vgs dependence of bulk charge effect 0.0V-1 Yes -
B0	0	0	0	-1e-20	0	0	-1e-20	0	-1e-20	0	0	Bulk charge effect coefficient for channel width 0.0m Yes -
B1	-3.347e-19	7.61e-18	2e-18	7.61e-18	-3.347e-19	7.61e-18	7.61e-18	7.61e-18	-3.5e-19	7.61e-18	7.61e-18	Bulk charge effect width offset 0.0m Yes -
KETA	0.04	0.04	0.04	0.04	0.04	0.04	0.04	0.04	0.04	0.04	0.04	Body-bias coefficient of bulk charge effect -0.047V-1 Yes -
A1	9.583e-10	4.31e-09	-8.63e-10	4.31e-09	9.583e-10	4.31e-09	4.31e-09	4.31e-09	1e-09	4.31e-09	4.31e-09	First non-saturation effect parameter 0.0V-1 Yes -
A2	1	1	0.99	1	1	1	1	1	1	1	1	Second non-saturation factor 1.0 Yes -
WINT	0	5e-09	0	5e-09	0	5e-09	5e-09	5e-09	5e-09	5e-09	5e-09	Channel-width offset parameter 0.0m No -
LINT	4e-08	1.05e-08	2.5e-08	7.5e-09	1.5e-08	5.25e-09	1.6e-08	3.75e-09	1.2e-08	2.7e-09	2e-09	Channel-length offset parameter 0.0m No -
WEFF	0	0	0	0	0	0	0	0	0	0	0	Coefficient of gate-bias dependence of Weff 0.0m/V Yes -
DMB	0	0	0	0	0	0	0	0	0	0	0	Coefficient of body bias dependence of Weff bias dependence 0.0m/V1/2 Yes -
VOFF	-0.1235	-0.13	-0.0798	-0.13	-0.03	-0.13	-0.15	-0.13	-0.15	-0.13	-0.13	Offset voltage in subthreshold region for large W and L -0.08V Yes -
VOFFL	0	0	0	0	0	0	0	0	0	0	0	Channel-length dependence of VOFF 0.0mV No -
MINV	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	0.05	Vgsteff fitting parameter for moderate inversion condition 0.0 Yes -
NFACROR	0.9	1.5	1.1	1.7	1.5	1.9	2	2.1	1.2	2.3	2.3	Subthreshold swing factor 1.0 Yes -
ETA0	30	30	30	30	30	30	30	30	30	30	30	DIBL coefficient in subthreshold region 0.08 Yes -
ETAB	0	0	0	0	0	0	0	0	0	0	0	Body-bias coefficient for the subthreshold DIBL effect -0.07V-1 Yes -
DSUB	0.8	0.1	0.52	0.1	0.6	0.1	1	0.1	2	0.1	0.078	DIBL coefficient exponent in subthreshold region DROUT Yes -
CT	0	0	0	0	0	0	0	0	0	0	0	Interface trap capacitance 0.0F/m2 Yes -
CDSC	0	0.0002	0	0.0002	0	0	0.0002	0	0.0002	0	0	Coupling capacitance between source/drain and channel 2.4e-4F/m2 Yes -
CDSCB	0	0	0	0	0	0	0	0	0	0	0	Body-bias sensitivity of Cdsc 0.0F/(Vm2) Yes -
CDSCD	0	0	0	0	0	0	0	0	0	0	0	Drain-bias sensitivity of Cdsc 0.0F/(Vm2) Yes -
PCLM	0.05	0.06	0.1	0.06	0.1	0.04	0.12	0.02	0.18	0.02	0.06	Channel length modulation parameter 1.3 Yes -
PDIBLC1	0.012	0.001	0.012	0.001	0.012	0.001	0.02	0.001	0.028	0.001	0.001	Parameter for DIBL effect on Rout 0.39 Yes -
PDIBLC2	0.0075	0.001	0.0075	0.001	0.0075	0.001	0.02	0.001	0.022	0.001	0.001	Parameter for DIBL effect on Rout 0.0086 Yes -
PDIBLCB	-0.0135	-0.005	-0.0135	-0.005	-0.0135	-0.005	-0.005	-0.005	-0.005	-0.005	-0.005	Body bias coefficient of DIBL effect on Rout 0.0V-1 Yes -
DROUT	0.018	0.5	0.28	0.5	2	0.5	0.5	0.5	0.45	0.5	0.5	Channel-length dependence of DIBL effect on Rout 0.56 Yes -
PSCBE1	8.66e+08	8.14e+08	8.66e+08	8.14e+08	8.66e+08	8.14e+08	8.14e+08	8.14e+08	8.14e+08	8.14e+08	8.14e+08	First substrate current induced body-effect parameter 4.24e8V/m Yes -
PSCBE2	1e-20	1e-20	1e-20	1e-20	1e-20	1e-20	1e-20	1e-20	1e-20	1e-20	1e-20	Second substrate current induced body-effect parameter 1.0e-5m/V Yes -
PG	-0.28	1e-20	-0.28	1e-20	-0.28	1e-20	1e-20	1e-20	1e-20	1e-20	1e-20	Gate-bias dependence of Early voltage 0.0 Yes -
DELTA	0.01	0.01	0.0101	0.01	0.01	0.01	0.01	0.01	0.01	0.01	0.01	(d in equation) Parameter for DC Vdseff 0.01V Yes -
FPROUT		0.2										

PDITS	0.08	0.08	0.08	0.2	0.08	0.2	0.01	0.01	Impact of drain-induced Vth shift on Rout 0.0V-1 Yes	Not modeled if binned PDITS=0; Fatal	
PDITSL	2.3e+06	2.3e+06	2.3e+06	2.3e+06	2.3e+06	2.3e+06	2.3e+06	2.3e+06	Channel-length dependence of drain-induced Vth shift for Rout 0.0m-1 No	Fatal error if	
PDITSD	0.23	0.23	0.23	0.23	0.23	0.23	0.23	0.23	Vds dependence of drain-induced Vth shift for Rout 0.0V-1 Yes		
LAMBDA									Velocity overshoot coefficient 0.0 Yes	If not given or (<=0.0), velocity overshoot will	
VTL									Thermal velocity 2.05e5[m/s] Yes	If not given or (<=0.0), source end thermal velo	
LC	4e-08	2e-08	2e-08	2e-08	2e-08	2e-08	2e-08	2e-08	Velocity back scattering coefficient 0.0[m] No	5e9[m] at room tem?perature	
XN									Velocity back scattering coefficient 3.0 Yes	-	
<b>Parameters for Asymmetric and Bias-Dependent Rds Model</b>											
RDSW	250	200	200	180	180	165	160	155	150	150	130
RDSWMIN		0	0	0	0	0	0	0	0	0	0
RDW		100	90	85	85	150	80	150	75	75	75
RDWMIN		0	0	0	0	0	0	0	0	0	0
RSW		100	90	85	85	150	80	150	75	75	75
RSWMIN		0	0	0	0	0	0	0	0	0	0
PRWG	0	0	0	0	0	0	0	0	0	0	0
PRWB	0	6.8e-11	0	6.8e-11	0	6.8e-11	6.8e-11	0	6.8e-11	0	0
WR	1	1	1	1	1	1	1	1	1	1	1
NRS											
NRD											
<b>Impact Ionization Current Model Parameters</b>											
ALPHA0	0	0.074	0	0.074	0	0.074	0.074	0.074	0.074	0.074	0.074
ALPHA1		0.005	0.005	0.005	0.005	0.005	0.005	0.005	0.005	0.005	0.005
BETA0	30	30	30	30	30	30	30	30	30	30	30
<b>Gate-Induced Drain Leakage Model Parameters</b>											
AGIDL	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002
BGIDL	2.1e+09	2.1e+09	2.1e+09	2.1e+09	2.1e+09	2.1e+09	2.1e+09	2.1e+09	2.1e+09	2.1e+09	2.1e+09
CGIDL	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002	0.0002
EGIDL	0.8	0.8	0.8	0.8	0.8	0.8	0.8	0.8	0.8	0.8	0.8
<b>Gate Dielectric Tunneling Current Model Parameters</b>											
AIGBACC	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012
BIGBACC	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028
CIGBACC	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002
NIGBACC	1	1	1	1	1	1	1	1	1	1	1
AIGBINV	0.014	0.014	0.014	0.014	0.014	0.014	0.014	0.014	0.014	0.014	0.014
BIGBINV	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004
CIGBINV	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004	0.004
FIGBINV	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1
NIGBINV	3	3	3	3	3	3	3	3	3	3	3
AIGC	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012
BIGC	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028
CIGC	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002
AIGSD	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012	0.012
BIGSD	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028	0.0028
CIGSD	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002	0.002
DLCIG											
NIIGC	1	1	1	1	1	1	1	1	1	1	1
FOKEDGE	1	1	1	1	1	1	1	1	1	1	1
FIGCD	1	1	1	1	1	1	1	1	1	1	1
NTOX	1	1	1	1	1	1	1	1	1	1	1
TOXREF	2.25e-09	2.05e-09	1.85e-09	1.7e-09	1.75e-09	1.4e-09	1.65e-09	1.2e-09			
<b>Charge and Capacitance Model Parameters</b>											
XPART	1	0	1	0	1	0	0	0	0	0	0
CGSO	2.786e-10	2.4e-10	2.75e-10	1.9e-10	3.493e-10	1.5e-10	5.458e-10	1.1e-10	6.238e-10	8.5e-11	6.5e-11
CGDO	2.786e-10	2.4e-10	2.75e-10	1.9e-10	3.493e-10	1.5e-10	5.458e-10	1.1e-10	6.238e-10	8.5e-11	6.5e-11
CGBO	0	2.56e-11	0	2.56e-11	0	2.56e-11	2.56e-11	2.56e-11	2.56e-11	2.56e-11	2.56e-11
CGSL	1.6e-10	2.653e-10	1.116e-10	2.653e-10	5.82e-11	2.653e-10	2.653e-10	2.495e-10	2.653e-10	2.653e-10	2.653e-10
CGDL	1.6e-10	2.653e-10	1.116e-10	2.653e-10	5.82e-11	2.653e-10	2.653e-10	2.495e-10	2.653e-10	2.653e-10	2.653e-10
CKAPPAS		0.03	0.03	0.03	0.03	0.03	0.03	0.01	0.03	0.03	0.03
CKAPPAD		0.03	0.03	0.03	0.03	0.03	0.03	0.01	0.03	0.03	0.03
CF	1.069e-10		1.113e-10		1.177e-10						
CIC	1e-07		5.475e-08		1e-07						
CLE	0.6		6.46		0.6						
DLC	4e-08		2e-08		2e-08						
DWC	0		0		0						
VFBCV	-1		-1		-1						
NOFF		0.9		0.9		0.9		0.9		0.9	0.9
VOFFCV		0.02		0.02		0.02		0.02		0.02	0.02
ACDE		1		1		1		1		1	1
MOIN		15		15		15		15		15	15
<b>High-Speed/RF Model Parameters</b>											
XRCRG1	12		12		12		12		12		12
XRCRG2	5		5		5		5		5		5
RBPB	5		5		5		5		5		5
RBPD	15		15		15		15		15		15
RBPS	15		15		15		15		15		15
RBSE	15		15		15		15		15		15
RBSB	15		15		15		15		15		15
GBMIN	1e-10		1e-10		1e-10		1e-10		1e-10		1e-10
<b>Flicker and Thermal Noise Model Parameters</b>											
NOIA											
NOIB											
NOIC											
EM											
AF											
EF	27	2.25e-09	27	2.05e-09	27	1.85e-09	1.7e-09	1.75e-09	1.4e-09	1.65e-09	1.2e-09
KF											
NTNOI											
TNOIA											
TNOIB											
RNOIA											
RNOIB											
<b>Layout-Dependent Parasitics Model Parameters</b>											
DMCG	0		0		0		0		0		0
DMCI	0		0		0		0		0		0
DMCG	0		0		0		0		0		0
DMCGT	0		0		0		0		0		0
NF											

Zero bias LDD resistance per unit width for RDSMOD=0 200.0 ohm(mm)WR Yes If negative, LDD resistance per unit width at high Vgs and zero Vbs for RDSMOD=0 0.0 ohm(mm)WR No - Zero bias lightly-doped drain resistance Rd(V) per unit width for RDS?MOD=1 100.0 ohm(mm)WR Lightly-doped drain resistance per unit width at high Vgs and zero Vbs for RDSMOD=1 0.0 Zero bias lightly-doped source resistance Rs(V) per unit width for RDS?MOD=1 100.0 ohm(mm) Lightly-doped source resistance per unit width at high Vgs and zero Vbs for RDSMOD=1 0.0 Gate-bias dependence of LDD resistance 1.0V-1 Yes - Body-bias dependence of LDD resistance 0.0V-0.5 Yes - Channel-width dependence parameter of LDD resistance 1.0 Yes - Number of source diffusion squares 1.0 No - Number of drain diffusion squares 1.0 No - First parameter of impact ionization current 0.0Am/V Yes - Isub parameter for length scaling 0.0A/V Yes - The second parameter of impact ionization current 30.0V Yes - Pre-exponential coefficient for GIDL 0.0mho Yes Igidl=0.0 if binned AGIDL =0.0 Exponential coefficient for GIDL 2.3e9V/m Yes Igidl=0.0 if binned BGIDL =0.0 Parameter for body-bias effect on GIDL 0.5V3 Yes - Fitting parameter for band bending for GIDL 0.8V Yes - Parameter for Igb in accumulation 0.43 (Fsz/g)0.5m-1 Yes - Parameter for Igb in accumulation 0.054 (Fsz/g)0.5 m-1V-1 Yes - Parameter for Igb in accumulation 0.075V-1 Yes - Parameter for Igb in accumulation 1.0 Yes Fatal error if binned value not positive Parameter for Igb in inversion 0.35 (Fsz/g)0.5m-1 Yes - Parameter for Igb in inversion 0.03 (Fsz/g)0.5 m-1V-1 Yes - Parameter for Igb in inversion 0.006V-1 Yes - Parameter for Igb in inversion 1.1V Yes - Parameter for Igb in inversion 1.1V Yes - Parameter for Igb in inversion 3.0 Yes Fatal error if binned value not positive Parameter for Igcs and Igcd 0.054 (NMOS) and 0.31 (PMOS) (Fsz/g)0.5m-1 Yes - Parameter for Igcs and Igcd 0.054 (NMOS) and 0.024 (PMOS) (Fsz/g)0.5 m-1V-1 Yes - Parameter for Igcs and Igcd 0.075 (NMOS) and 0.03 (PMOS) V-1 Yes - Parameter for Igcs and Igcd 0.43 (NMOS) and 0.31 (PMOS) (Fsz/g)0.5m-1 Yes - Parameter for Igcs and Igcd 0.054 (NMOS) and 0.024 (PMOS) (Fsz/g)0.5 m-1V-1 Yes - Parameter for Igcs and Igcd 0.075 (NMOS) and 0.03 (PMOS) V-1 Yes - Source/drain overlap length for Igcs and Igcd LINT Yes - Parameter for Igcs, Igcd, Igcs and Igcd 1.0 Yes Fatal error if binned value not positive Factor for the gate oxide thickness in source/drain overlap regions 1.0 Y Vds dependence of Igcs and Igcd 1.0 Yes Fatal error if binned value not positive Exponent for the gate oxide ratio 1.0 Yes - Nominal gate oxide thickness for gate dielectric tunneling current model only 3.0e-9m N Charge partition parameter 0.0 No - Non LDD region source-gate overlap capacitance per unit channel width calculated (F/m) No Note-6 Non LDD region drain-gate overlap capacitance per unit channel width calculated (F/m) No Note-6 Gate-bulk overlap capacitance per unit channel length 0.0 F/m Note-6 Overlap capacitance between gate and lightly-doped source region 0.0F/m Yes - Overlap capacitance between gate and lightly-doped source region 0.0F/m Yes - Coefficient of bias-dependent overlap capacitance for the source side 0.6V Yes - Coefficient of bias-dependent overlap capacitance for the drain side CKAPPAS Yes - Fringing field capacitance calculated (F/m) Yes Note-7 Constant term for the short channel model 1.0e-7m Yes - Exponential term for the short channel model 0.6 Yes - Channel-length offset parameter for CV model LINT (m) No - Channel-width offset parameter for CV model WINT (m) No - Flat-band voltage parameter (for CAPMOD=0 only) -1.0V Yes - CV parameter inVgsteff,CV for weak to strong inversion 1.0 Yes - CV parameter inVgsteff,CV for weak to strong inversion 0.0V Yes - Exponential coeff for gate thickness in CAPMOD=2 for accum?lation and depletion regions 1.0m/V Coefficient for the gate-bias dependent surface potential 15.0 Yes - Parameter for distributed channel-resistance effect for both intrinsic-input resistance and Parameter account for excess channel diffusion resist for both intrinsic input resist and ch Resistance between bNodePrime and bNode 50.0ohm No If less than 1.0e-3ohm, reset to 1.0e-3ohm Resistance between bNodePrime and dBNode 50.0ohm No If less than 1.0e-3ohm, reset to 1.0e-3ohm Resistance between bNodePrime and sNode 50.0ohm No If less than 1.0e-3ohm, reset to 1.0e-3ohm Resistance connected between dBNode and bNode 50.0ohm No less than 1.0e-3ohm, reset to 1.0e-3ohm Resistance connected between sNode and bNode 50.0ohm No If less than 1 Conductance in parallel with each of the five substrate resistances Flicker noise parameter A 6.25e41 (eV)-1sl?EFM=3 for NMOS; 6.188e40 (eV)-1sl?EFM=3 for PMOS No - Flicker noise parameter B 3.125e26 (eV)-1sl?EFM=1 for NMOS; 1.5e25 (eV)-1sl?EFM=1 for PMOS No - Flicker noise parameter C 8.75 (eV)-1sl-EPm No - Saturation field 4.1e7V/m No - Flicker noise exponent 1.0 No - Flicker noise frequency exponent 1.0 No - Flicker noise coefficient 0.0 A2-EFS1-EF F No - Noise factor for short-channel devices for TNOIMOD=0 only 1.0 No - Coefficient of channel-length dependence of total channel thermal noise 1.5E6 No - Channel-length dependence parameter for channel thermal noise partitioning 3.5E6 No - Thermal Noise Coefficient 0.577 No - Thermal Noise Coefficient 0.37 No - Distance from S/D contact center to the gate edge 0.0m No - Distance S/D contact center to isolation edge in the channel-length direction DMCG No - Same as DMCG but for merged device only 0.0m No - DMCG of test structures 0.0m No - Number of device fingers 1 No Fatal error if less than one



WVC  
WWLC

Coefficient of width dependence for CV channel width offset WW No -  
Coefficient of length and width cross-term dependence for CV channel width offset WWL No -

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**Range Parameters for Model Application**-----  
LMIN 1.8e-07 1.3e-07 1e-07 Minimum channel length 0.0m No -  
LMAX 1.8e-07 1.3e-07 1e-07 Maximum channel length 1.0m No -  
WMIN 1.8e-07 0 1.3e-07 0 1e-07 0 0 0 0 0 0 Minimum channel width 0.0m No -  
WMAX 0.0001 0.0001 0.0001 Maximum channel width 1.0m No -